

Product Information Sheet

MATERIAL ID: EPO-TEK® OG169

Date: 08/2007 **Per:**

Rev: II

Material Description: A single component, UV curable epoxy, designed for adhesive, sealing,

coating and encapsulating applications found in semiconductor, electrooptics, fiber optics, medical, and scientific/OEM industries. It is nonyellowing after cure per ASTM D1925. Complies with USP Class VI

biocompatibility standards.

Number of Components: Single **Mix Ratio by weight:** N/A

Cure Schedule (minimum)* 100mW/cm² for >4 minutes @ 320-500 nm (depending on thickness)

Specific Gravity: 1.12 --- Part A: Part B:

Pot Life: N/A

Shelf Life: One year at room temperature

NOTE: Container(s) should be kept closed in a dark location when not in use.

*Please see Applications Note(s) available on our website.

MATERIAL CHARACTERISTICS: To be used as a guide only, not as a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results. * denotes test on lot acceptance basis; Cure condition: UV Cure + 150°C/varies as required

PHYSICAL PROPERTIES:				
*Color (before cure):	Clear/Colorless	Die Shear @ 23°C:	≥ 10 Kg / 3,400 psi	
*Consistency:	Pourable liquid	Degradation Temp:	307 ° C	
*Viscosity (23°C):		Weight Loss:		
@ 100 rpm	100 - 200 cPs	@ 200°C:	0.74 %	
Thixotropic Index:	N/A	@ 250°C:	1.83 %	
*Glass Transition	\geq 80 ° C (Post-Cure	@ 300°C:	8.22 %	
Dynamic Scan 20—200°C; Ramp -10—200°C @ 20°C/Min)		Operating Temp:		
Coefficient of Thermal Expansion (CTE):		Continuous:	-55° C to $+150^{\circ}$ C	
Below Tg:	74 x 10 ⁻⁶ in/in°C	Intermittent:	- 55° C to + 250° C	
Above Tg:	156 x 10⁻⁶ in/in°C	Storage Modulus @ 23°C:	233,044 psi	
Shore D Hardness:	86	*Particle Size:	N/A	

OPTICAL PROPERTIES @ 23°C:				
Spectral Transmission:	>98 % @ 460-1660 nm	Refractive Index (uncured):	1.5084 @ 589 nm	
	>94 % @ 400 nm			

EPOXY TECHNOLOGY, INC.
14 FORTUNE DRIVE, BILLERICA, MA 01821 (978) 667-3805, FAX (978) 663-9782
WEB SITE: www.epotek.com